



Session 1A/B Agenda

- Opening Remarks
 - Ira Feldman, General Chair
- Keynote Preview
 - “Materials Science Innovation in Advanced Packaging”
 - Ross Berntson, Indium
- Market Reports
 - Marketplace Report
 - Ira Feldman, Feldman Engineering
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You can't change the way the wind
blows but you *can* adjust your sails

- Cora L.V. Hatch 1859/paraphrased



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TestConX Workshop Committee

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Ira Feldman
Feldman Engineering Corp.

Registration

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Test Tooling Solutions

Paul Boyce
Advantage Specialist

Susan Kinne
TestConX Registration Office

TestConX EXPO

Owen Prillaman, Chair
TechConnect Sales and Distribution Inc.



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AK Technology Leadership

Ila Pal, Co-Chair
Ironwood Electronics

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R&D Altanova

Jason Mroczkowski
Cohu

Marc Möessinger
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Texas Instruments

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Valts Treibergs
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Mohan Prabhugoud
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Hongjun Yao
Qualcomm



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TestConX Overview

March
2021

- Welcome to TestConX!
- **TestConX** Workshop
 - Preeminent event for all practical aspects of electronics testing
 - A scope that incorporates next-generation solutions to test and burn-in challenges while also providing vital, current information on traditional technologies
- *Connecting Electronic Test Professionals to Solutions*
- Latest Information About Test & Burn-in of Packaged IC's
- Extensive & Diverse Technical Program
- The Latest Products & Services at TestConX EXPO
- Many Networking Opportunities
- Feedback & Suggestions are Encouraged
- Informal and Casual Throughout All Sessions & Activities



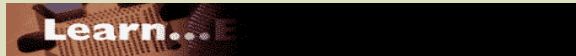
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Core Values

- **Connecting Electronic Test Professionals to Solutions**
 - Premier Event ♦ Cutting Edge ♦ Staying Ahead



Technical Program



TestConX EXPO



Networking Opportunities



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5th Annual TestConX China Shanghai - October 29, 2019



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In memory of Roger E. Weiss



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Early BiTS



BiTS 2002 Presentation



BiTS EXPO 2003 with David Barnum



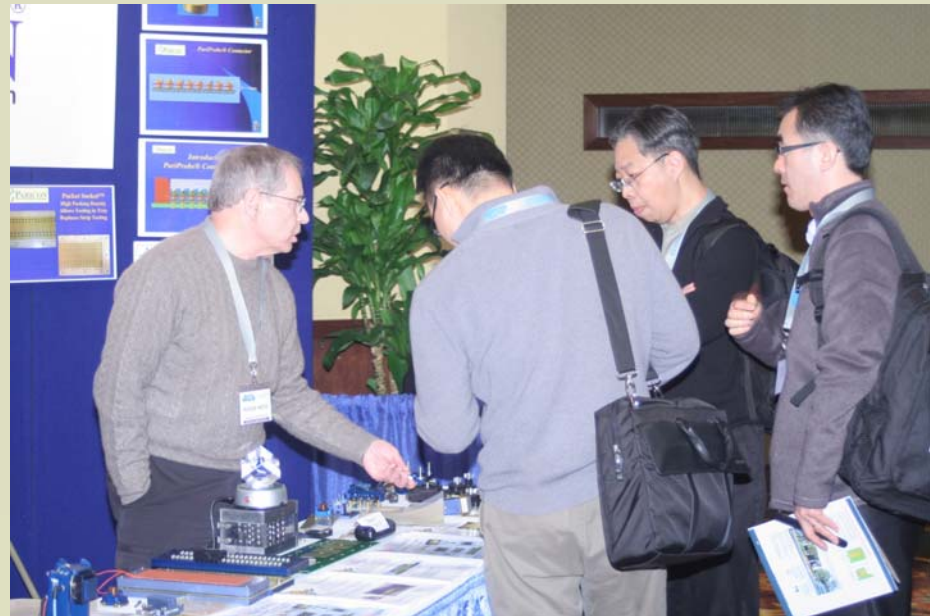
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BiTS



BiTS 2009 Presentation



BiTS EXPO 2010



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Awards – Attendee Choice 2019

“SLT Test Fundamentals and Challenges”

John Yi - AMD



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TestConX 2020 Awards

- Best Presentation
- Best Poster
- Best Data
- Most Inspirational
- Most Educational
- Attendee Choice (3x)



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testconx.org

Your Complete Source For Information About TestConX

Current Workshop

- Call For Papers
- EXPO & Sponsorships
- Advance/Final Program
- Registration Information & Forms;
Register On-line
- Author Information
- Hotel Information/Travel

Features

- Committee Members
- Contact TestConX - Add to Mailing List
& Inquiries
- Links to Other Websites
- 'Press' About TestConX
- Archive of past BiTS & TestConX
- Search TestConX Feature

Plus Premium Archive...



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TestConX Premium Archive

- Multimedia
 - Audio with synchronized slides & pointer
 - BiTS 2014 – 2018 / TestConX 2019 - 2020
 - BiTS China 2015 – 2017 / TestConX China 2018-2019
 - TestConX 2020 Interactive Sessions posted next week
- Additional content
 - Tutorials
- Subscription Model
 - TestConX 2020 Virtual Event Participants – subscription until TestConX 2021
 - Subscriber – Nominal Fee

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Future Events – Save the Dates!

TestConX Korea

Thursday October 22, 2020
Incheon



Tuesday October 27, 2020
Shanghai



March 7 – 10, 2021
Mesa, Arizona

Please let the TestConX Office know of your interest!

Interactive Sessions – May 11-13, 2020

Session	Pacific Time	Central Europe	Japan & Korea	China
1A	Monday May 11, 2020			
	7 - 9 am	1600-1800	2300 - 0100	2200-2400
1B	11-May	Tuesday May 12, 2020		
	5 - 7 pm	0200-0400	0900-1100	0800-1000
2A	Tuesday May 12, 2020			
	7 - 9 am	1600-1800	2300 - 0100	2200-2400
2B	12-May	Wednesday May 13, 2020		
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3A	Wednesday May 13, 2020			
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3B	13-May	Thursday May 14, 2020		
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- Keynote
Address

TestConX Workshop 2022 Schedule

Monday March 8, 2021

“Materials Science Innovation in Advanced Packaging”

Ross Berntson

Indium Corporation

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bringing technology to life



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21

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